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APPLICATION NO.	FILING	G DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/659,585	09/11/2003		Shunpei Yamazaki	0756-7196	7079
31780	7590	10/17/2005		EXAMINER	
ERIC ROBI	NSON		DOTY, HEAT	DOTY, HEATHER ANNE	
PMB 955 21010 SOUT	HRANK ST			ART UNIT	PAPER NUMBER
POTOMAC 1				2813	· _ /·

DATE MAILED: 10/17/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	:
	10/659,585	YAMAZAKI ET AL.	
Office Action Summary	Examiner	Art Unit	(Prof)
	Heather A. Doty	2813	
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the o	correspondence addre	ss
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If NO period for reply is specified above, the maximum statutory period w  - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tir rill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	N. mely filed the mailing date of this comm ED (35 U.S.C. § 133).	;
Status			
1) Responsive to communication(s) filed on 25 Ju	<u>ıly 2005</u> .		
2a) ☐ This action is <b>FINAL</b> . 2b) ☒ This	action is non-final.		
3) Since this application is in condition for allowar	nce except for formal matters, pro	osecution as to the m	erits is
closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 4	53 O.G. 213.	
Disposition of Claims			:
4) Claim(s) 1-50 is/are pending in the application.			
4a) Of the above claim(s) 4,5,7,8,10,11,13,14 a	nnd 16 is/are withdrawn from con	sideration.	:
5) Claim(s) 2,3,6,9,12,15 and 17-50 is/are allowed	d.		
6)⊠ Claim(s) <u>1</u> is/are rejected.	:		•
7) Claim(s) is/are objected to.	•		
8) Claim(s) are subject to restriction and/or	r election requirement.		·
Application Papers			
9) ☐ The specification is objected to by the Examine 10) ☑ The drawing(s) filed on 11 September 2003 is/a Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct 11) ☐ The oath or declaration is objected to by the Ex	are: a) $\square$ accepted or b) $\square$ object drawing(s) be held in abeyance. Se ion is required if the drawing(s) is ob-	e 37 CFR 1.85(a). ojected to. See 37 CFR	1.121(d).
Priority under 35 U.S.C. § 119	·		;
a) All b) Some * c) None of:  1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the priority documents application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Applicat ity documents have been receiv (PCT Rule 17.2(a)).	ion No ed in this National Sta	3ge :
Attachment(s)			
1) Notice of References Cited (PTO-892)	4) Interview Summary	/ (PTO-413)	
2) Notice of Draftsperson's Patent Drawing Review (PTO-948)	Paper No(s)/Mail D	ate	
3) ☑ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 9/11/03, 12/12/03. •	5) ☐ Notice of Informal F 6) ☑ Other: <u>IDS 3/22304</u>	Patent Application (PTO-15 4.7/25/05.	(2)
S. Ratest and Trademark Office	.,		

## **DETAILED ACTION**

#### Election/Restrictions

Applicant's election of 2, 3, 6, 9, 12, 15, and 17 in the reply filed on 7/15/2005 is acknowledged. Because applicant did not distinctly and specifically point out the supposed errors in the restriction requirement, the election has been treated as an election without traverse (MPEP § 818.03(a)). Additionally, the examiner agrees that claim 1 is generic to all species, so claims 1, 2, 3, 6, 9, 12, 15, 17, and 18-50 are subject to examination.

#### Information Disclosure Statement

The examiner is unable to locate in the application file the non-patent literature by Tsutsui et al. listed in the Information Disclosure Statement filed 9/11/2003. Therefore only the abstract has been considered, a copy of which is included with this Office action.

# Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claim 1 is rejected under 35 U.S.C. 103(a) as being unpatentable over Teong (U.S. 5,693,563) in view of Moritz et al. (U.S. 4,659,650) and Douglas (U.S. 4,100,499).

Regarding claim 1, Teong teaches a method of manufacturing a semiconductor device comprising the steps of:

forming a wiring comprising at least a laminate of a first conductive film with a property as a barrier and a second conductive film containing copper as its main component, said step of forming a wiring including the steps of:

- (i) forming a first conductive film (barrier layer 4 in Fig. 1; column 4, lines 3-6) over an insulating surface (1 in Fig. 1; column 3, lines 61-63);
  - (ii) etching the first conductive film (column 4, lines 7-9);
- (iii) forming the second conductive film on the first conductive film (copper layer 8 in Fig. 4; column 4, lines 26-29); and
  - (iv) reducing a width of the second conductive film (column 4, lines 29-33).

Teong does not teach that the copper layer is formed through an opening of a mask or that the width of the second conductive film is reduced with dry etching.

Moritz et al. teaches depositing copper through an opening of a lift-off mask (column 5, lines 42-52) using a method that produces low and uniform contact resistance (column 2, lines 31-32).

Therefore, at the time of the invention, it would have been obvious to one of ordinary skill in the art to use the method taught by Teong and further deposit the copper layer through the lift-off mask taught by Moritz et al. The motivation for doing so at the time of the invention would have been to produce low and uniform contact resistance between layers, as taught by Moritz et al.

Douglas teaches a method of dry-etching copper (column 2, lines 50-55) that offers the advantage over wet-etching processes of not contaminating the integrated

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circuit (column 1, lines 56-59), and additionally offers greater control in etching features (column 1, lines 63-66; column 3, lines 6-7).

Therefore, at the time of the invention, it would have been obvious to one of ordinary skill in the art to use the method taught by Teong and Moritz et al. together, and also use dry etching to reduce the width of the second conductive layer, as taught by Douglas. The motivation for doing so at the time of the invention would have been because this etching method does not contaminate the device and offers greater control in etching features than wet etch processes do, as expressly taught by Douglas.

# Allowable Subject Matter

Claims 2, 3, 6, 9, 12, 15, and 17-50 are allowed.

The following is a statement of reasons for the indication of allowable subject matter:

Prior art does not teach or suggest, in combination with the other claimed limitations, a method of manufacturing a semiconductor device that comprises forming a wiring according to the method taught by claim 1 and then using the wiring as a mask to form an impurity region. Nakanishi et al. (U.S. 6,265,247) teaches a method of manufacturing a semiconductor device comprising substantially all of the steps recited in claims 2 and 18, except that the gate used as a mask to form an impurity region is formed through sputtering a metal with a high melting point such as chromium or molybdenum. However, there is no reason to combine this teaching with the combined teachings of Teong, Moritz et al., and Douglas to arrive at the invention as claimed in claims 2, 3, 6, 9, 12, 15, and 17-50. The method taught by Teong and modified by

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Moritz et al. and Douglas (see U.S.C. 103(a) rejection above) is primarily a dual-

damascene method, which would not be appropriate to use as a mask to form an

impurity region.

Conclusion

Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Heather A. Doty, whose telephone number is 571-272-

8429. The examiner can normally be reached on M-F, 8:30 - 5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Carl Whitehead, Jr., can be reached at 571-272-1702. The fax phone

number for the organization where this application or proceeding is assigned is 571-

273-8300.

Information regarding the status of an application may be obtained from the

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